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# DMC3025LSD-13

**Diodes Incorporated** 

MOSFET 30V Comp ENH Mode 25 to 30V MosFET

Any questions, please feel free to contact us. info@kaimte.com





#### 30V COMPLEMENTARY ENHANCEMENT MODE MOSFET

#### **Product Summary**

| Device    | V <sub>(BR)DSS</sub> | R <sub>DS(ON) max</sub>       | Package | I <sub>D MAX</sub><br>T <sub>A</sub> = +25℃ |
|-----------|----------------------|-------------------------------|---------|---|
| N-Channel | 30V                  | $20m\Omega @ V_{GS} = 10V$    |         | 8.5A  |
|           |                      | $32m\Omega$ @ $V_{GS} = 4.5V$ | SO-8    | 7.0A  |
| P-Channel | -30V                 | 45mΩ @ V <sub>GS</sub> = -10V | 30-8    | -5.5A                                       |
|           |                      | $85m\Omega @ V_{GS} = -4.5V$  |         | -4.1A                                       |

#### **Description**

This MOSFET is designed to minimize the on-state resistance  $(R_{DS(ON)})$  and yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

#### **Applications**

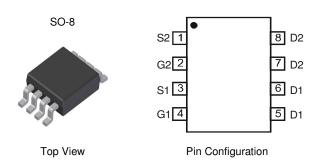
- DC Motor Control
- DC-AC Inverters

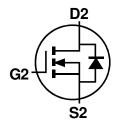
#### **Features**

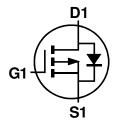
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed Over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.008 grams (Approximate)







**Q2 N-CHANNEL MOSFET** 

Q1 P-CHANNEL MOSFET

**Equivalent Circuit** 

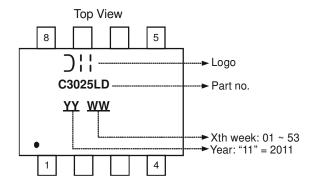
#### Ordering Information (Note 4)

| Part Number   | Case | Packaging         |
|---------------|------|-------------------|
| DMC3025LSD-13 | SO-8 | 2,500/Tape & Reel |

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

#### **Marking Information**





## Maximum Ratings N-CHANNEL— Q2 (@T<sub>A</sub> = +25 ℃, unless otherwise specified.)

| Characteristic   |                 |                                  | Symbol           | Value      | Units |
|--|-----------------|----------------------------------|------------------|------------|-------|
| Drain-Source Voltage                                     |                 |                                  | V <sub>DSS</sub> | 30         | V     |
| Gate-Source Voltage                                      |                 |                                  | V <sub>GSS</sub> | ±20        | V     |
|  |                 | $T_A = +25$ °C<br>$T_A = +70$ °C | ID               | 6.5<br>5.1 | А     |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V  | t<10s           | $T_A = +25$ °C<br>$T_A = +70$ °C | l <sub>D</sub>   | 8.5<br>6.8 | А     |
| Continuous Dunin Courset (Alata 5) V 4 5V                | Steady<br>State | $T_A = +25$ °C<br>$T_A = +70$ °C | l <sub>D</sub>   | 5.3<br>4.1 | А     |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = 4.5V | t<10s           | $T_A = +25$ °C<br>$T_A = +70$ °C | ID               | 7.0<br>5.5 | А     |
| Maximum Continuous Body Diode Forward Current            | (Note 5)        |                                  | Is               | 2          | Α     |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%)       |                 |                                  | I <sub>DM</sub>  | 60         | Α     |
| Pulsed Body Diode Current (10µs pulse, duty cycle = 1%)  |                 |                                  | I <sub>SM</sub>  | 60         | Α     |
| Avalanche Current (Note 7) L = 0.1mH                     |                 |                                  | I <sub>AS</sub>  | 14         | Α     |
| Avalanche Energy (Note 7) L = 0.1mH                      |                 |                                  | Eas              | 10         | mJ    |

# Maximum Ratings P-CHANNEL— Q1 (@T<sub>A</sub> = +25 ℃, unless otherwise specified.)

| Characteristic  |                 |                                  | Symbol           | Value        | Units |
|---|-----------------|----------------------------------|------------------|--------------|-------|
| Drain-Source Voltage                                      |                 |                                  | V <sub>DSS</sub> | -30          | V     |
| Gate-Source Voltage                                       |                 |                                  | V <sub>GSS</sub> | ±20          | V     |
|   |                 | $T_A = +25$ °C<br>$T_A = +70$ °C | I <sub>D</sub>   | -4.2<br>-3.2 | А     |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = -10V  | t<10s           | $T_A = +25$ °C<br>$T_A = +70$ °C | I <sub>D</sub>   | -5.5<br>-4.3 | А     |
| Centinuous Drain Current (Note 5) // 45/                  | Steady<br>State | $T_A = +25$ °C<br>$T_A = +70$ °C | I <sub>D</sub>   | -3.5<br>-2.3 | А     |
| Continuous Drain Current (Note 5) V <sub>GS</sub> = -4.5V | t<10s           | $T_A = +25$ °C<br>$T_A = +70$ °C | I <sub>D</sub>   | -4.1<br>-3.2 | А     |
| Maximum Continuous Body Diode Forward Current (Note 5)    |                 |                                  | Is               | -2           | Α     |
| Pulsed Drain Current (10µs pulse, duty cycle = 1%)        |                 |                                  | I <sub>DM</sub>  | -30          | Α     |
| Pulsed Body Diode Current (10µs pulse, duty cycle = 1%)   |                 |                                  | I <sub>SM</sub>  | -30          | Α     |
| Avalanche Current (Note 7) L = 0.1mH                      |                 |                                  | I <sub>AS</sub>  | -14          | Α     |
| Avalanche Energy (Note 7) L = 0.1mH                       |                 |                                  | Eas              | 10           | mJ    |

#### **Thermal Characteristics**

| Characteristic                                   | Symbol                           | Value           | Units |      |
|--|----------------------------------|-----------------|-------|------|
| Total Dayyar Dissination (Note 6)                | T <sub>A</sub> = +25 ℃           | В               | 1.2   |      |
| Total Power Dissipation (Note 6)                 | T <sub>A</sub> = +70 °C          | $P_D$           | 0.77  | W    |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State                     | Б               | 104   | °C/W |
| Thermal Resistance, Junction to Ambient (Note 6) | t<10s                            | $R_{\theta JA}$ | 62    | C/VV |
| Total Dayyar Dissination (Note 5)                | T <sub>A</sub> = +25 °C          | В               | 1.5   | W    |
| Total Power Dissipation (Note 5)                 | T <sub>A</sub> = +70 °C          | $P_D$           | 0.95  | VV   |
| Thermal Desistance, Junction to Ambient (Note E) | Steady State                     | Б               | 83    |      |
| Thermal Resistance, Junction to Ambient (Note 5) | t<10s                            | $R_{\theta JA}$ | 49    | °C/W |
| Thermal Resistance, Junction to Case (Note 5)    | $R_{	heta JC}$                   | 15              |       |      |
| Operating and Storage Temperature Range          | T <sub>J,</sub> T <sub>STG</sub> | -55 to +150     | ℃     |      |

Notes:

<sup>5.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



#### Electrical Characteristics N-CHANNEL— Q2 (@T<sub>A</sub> = +25 ℃, unless otherwise specified.)

| Characteristic                             | Symbol               | Min | Тур  | Max | Unit  | Test Condition  |
|--|----------------------|-----|------|-----|-------|---|
| OFF CHARACTERISTICS (Note 8)               |                      |     |      |     |       |   |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>    | 30  |      | _   | V     | $V_{GS} = 0V, I_D = 250\mu A$   |
| Zero Gate Voltage Drain Current            | I <sub>DSS</sub>     | _   | _    | 1   | μA    | $V_{DS} = 30V, V_{GS} = 0V$   |
| Gate-Source Leakage                        | I <sub>GSS</sub>     | _   | _    | ±1  | μΑ    | $V_{GS} = \pm 20V, V_{DS} = 0V$   |
| ON CHARACTERISTICS (Note 8)                |                      |     |      |     |       |   |
| Gate Threshold Voltage                     | V <sub>GS(th)</sub>  | 1.0 |      | 2.0 | V     | $V_{DS}=V_{GS},\ I_D=250\mu A$  |
| Static Drain-Source On-Resistance          | D                    | _   | 15   | 20  | mΩ    | $V_{GS} = 10V, I_D = 7.4A$  |
| Static Diani-Source Off-Nesistance         | R <sub>DS (ON)</sub> | _   | 23   | 32  | 11122 | $V_{GS} = 4.5V, I_D = 6A$   |
| Forward Transfer Admittance                | Y <sub>fs</sub>      | _   | 8    | _   | S     | $V_{DS} = 5V, I_{D} = 10A$  |
| Diode Forward Voltage                      | V <sub>SD</sub>      | _   | 0.70 | 1.2 | V     | $V_{GS} = 0V, I_{S} = 1A$   |
| DYNAMIC CHARACTERISTICS (Note 9)           |                      |     |      |     |       |   |
| Input Capacitance                          | C <sub>iss</sub>     | _   | 501  | _   |       | V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V,<br>f = 1.0MHz                          |
| Output Capacitance                         | Coss                 | _   | 72   | _   | pF    |   |
| Reverse Transfer Capacitance               | C <sub>rss</sub>     | _   | 57   | _   |       |   |
| Gate Resistance                            | $R_g$                | _   | 1.84 | _   | Ω     | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$  |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | Qg                   | _   | 4.6  | _   |       |   |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | Qg                   | _   | 9.8  | _   | nC    | V 45V L 40A   |
| Gate-Source Charge                         | Q <sub>gs</sub>      | _   | 1.6  | _   | IIC   | $V_{DS} = 15V, I_{D} = 10A$   |
| Gate-Drain Charge                          | Q <sub>gd</sub>      | _   | 2.0  | _   |       |   |
| Turn-On Delay Time                         | t <sub>D(on)</sub>   | _   | 3.9  | _   |       | $\begin{split} V_{DD} &= 15V, V_{GS} = 10V,\\ R_G &= 6\Omega, I_D = 1A \end{split}$ |
| Turn-On Rise Time                          | t <sub>r</sub>       | _   | 4.2  | _   |       |   |
| Turn-Off Delay Time                        | t <sub>D(off)</sub>  | _   | 16.6 | _   | ns    |   |
| Turn-Off Fall Time                         | t <sub>f</sub>       | _   | 5.8  | _   |       |   |
| Reverse Recovery Time                      | t <sub>rr</sub>      | _   | 5.5  | _   | ns    | 1 104 di/dt E004/u-   |
| Reverse Recovery Charge                    | Q <sub>rr</sub>      | _   | 2.6  | _   | nC    | I <sub>F</sub> = 12A, di/dt = 500A/μs   |



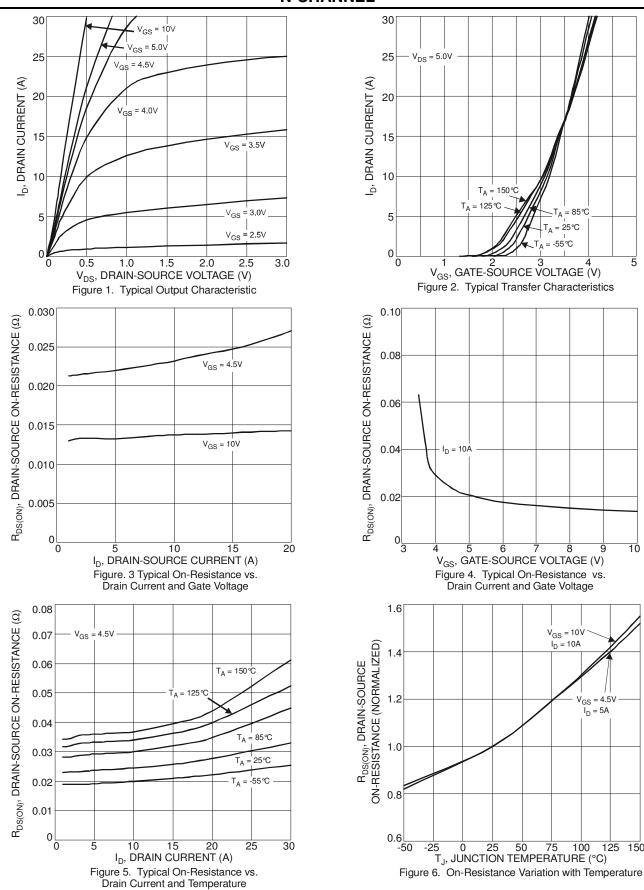
### Electrical Characteristics P-CHANNEL – Q1 (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

| Characteristic                             | Symbol               | Min  | Тур  | Max  | Unit  | Test Condition                                |
|--|----------------------|------|------|------|-------|---|
| DFF CHARACTERISTICS (Note 8)               |                      |      |      |      |       |   |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>    | -30  | _    | _    | V     | $V_{GS} = 0V, I_D = -250\mu A$                |
| Zero Gate Voltage Drain Current            | I <sub>DSS</sub>     | _    | _    | -1   | μΑ    | $V_{DS} = -30V, V_{GS} = 0V$                  |
| Gate-Source Leakage                        | I <sub>GSS</sub>     | _    | _    | ±100 | nA    | $V_{GS} = \pm 20V, V_{DS} = 0V$               |
| ON CHARACTERISTICS (Note 8)                |                      |      |      |      |       |   |
| Gate Threshold Voltage                     | V <sub>GS(th)</sub>  | -1.0 | _    | -2.0 | V     | $V_{DS} = V_{GS}, I_{D} = -250 \mu A$         |
| Static Drain-Source On-Resistance          | D                    | _    | 38   | 45   | mΩ    | $V_{GS} = -10V, I_D = -5.2A$                  |
| Static Drain-Source On-Nesistance          | R <sub>DS (ON)</sub> | _    | 65   | 85   | 11122 | $V_{GS} = -4.5V, I_D = -4A$                   |
| Forward Transfer Admittance                | Y <sub>fs</sub>      | _    | 5    | _    | S     | $V_{DS} = -5V, I_{D} = -5.2A$                 |
| Diode Forward Voltage                      | $V_{SD}$             | _    | -0.7 | -1.2 | V     | $V_{GS} = 0V, I_{S} = -1A$                    |
| DYNAMIC CHARACTERISTICS (Note 9)           |                      |      |      |      |       |   |
| Input Capacitance                          | C <sub>iss</sub>     | _    | 590  | _    | рF    | .,  |
| Output Capacitance                         | Coss                 | _    | 69   | _    | рF    | $V_{DS} = -25V, V_{GS} = 0V,$<br>- f = 1.0MHz |
| Reverse Transfer Capacitance               | C <sub>rss</sub>     | _    | 53   | _    | рF    | -1 = 1.0ivii iz                               |
| Gate Resistance                            | $R_g$                | _    | 11   | _    | Ω     | $V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$        |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | $Q_g$                | _    | 5.1  | _    | nC    |   |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | Qg                   | _    | 10.5 | _    | nC    | -Vps = -15V. lp = -6A                         |
| Gate-Source Charge                         | Q <sub>gs</sub>      | _    | 1.8  | _    | nC    | VDS = -15V, ID = -6A                          |
| Gate-Drain Charge                          | $Q_{gd}$             | _    | 1.9  | _    | nC    |   |
| Turn-On Delay Time                         | t <sub>D(on)</sub>   | _    | 6.8  | _    | ns    |   |
| Turn-On Rise Time                          | t <sub>r</sub>       | _    | 4.9  | _    | ns    | $V_{DD} = -15V, V_{GS} = -10V,$               |
| Turn-Off Delay Time                        | t <sub>D(off)</sub>  | _    | 28.4 | _    | ns    | $R_G = 6\Omega$ , $I_D = -1A$                 |
| Turn-Off Fall Time                         | t <sub>f</sub>       | _    | 12.4 | _    | ns    | 1   |
| Reverse Recovery Time                      | t <sub>rr</sub>      | _    | 14   | _    | ns    | 1 104 4:/44 5004/                             |
| Reverse Recovery Charge                    | Q <sub>rr</sub>      | _    | 11   |      | nC    | I <sub>F</sub> = 12A, di/dt = 500A/μs         |

<sup>7.</sup> IAS and EAS rating are based on low frequency and duty cycles to keep  $T_J$  = +25 °C. 8. Short duration pulse test used to minimize self-heating effect. 9. Guaranteed by design. Not subject to product testing.



#### **N-CHANNEL**





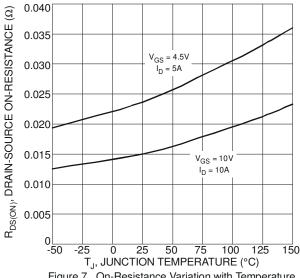
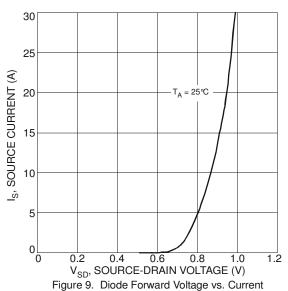


Figure 7. On-Resistance Variation with Temperature



10 V<sub>GS</sub> GATE THRESHOLD VOLTAGE (V) V<sub>DS</sub> = 15V 8  $I_D = 10A$ 0 1  $Q_g$ , TOTAL GATE CHARGE (nC) 12 Figure 11. Gate Charge

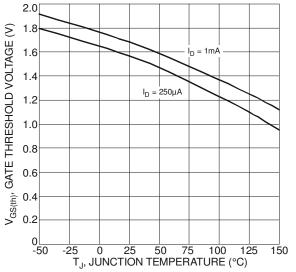
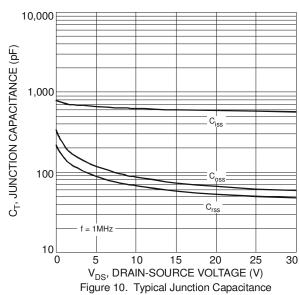


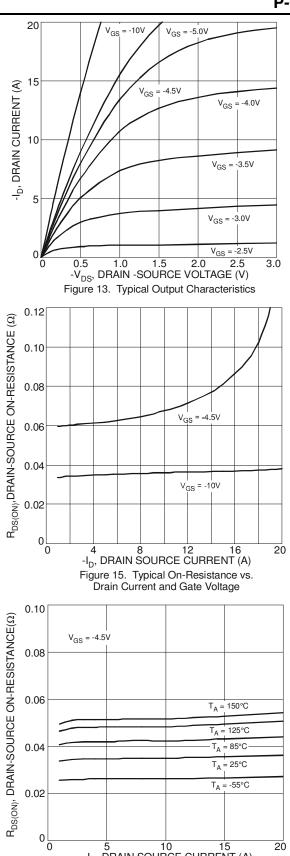
Figure 8 Gate Threshold Variation vs. Ambient Temperature



100E R<sub>DS(on)</sub> Limited DRAIN CURRENT (A) \_ \_ \_ \_ \_ \_ \_ 0.1  $T_{J(max)} = 150 \, ^{\circ}$   $T_{A} = 25 \, ^{\circ}$ Single Pulse 0.01 1 10 V<sub>DS</sub>, DRAIN-SOURCE VOLTAGE (V) 0.1 100 Figure 12. SOA, Safe Operation Area



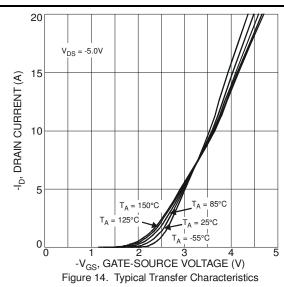
#### **P-CHANNEL**

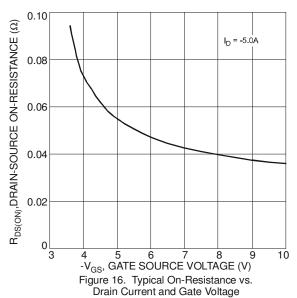


5 10 15 -I<sub>D</sub>, DRAIN SOURCE CURRENT (A)

Figure 17. Typical On-Resistance vs.

Drain Current and Temperature





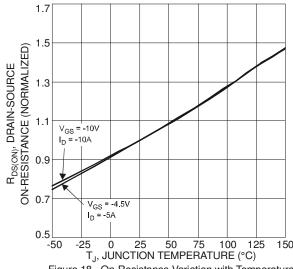


Figure 18. On-Resistance Variation with Temperature

20



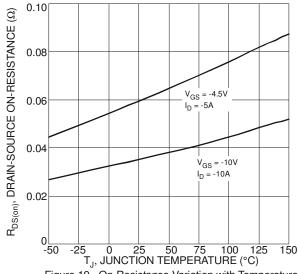
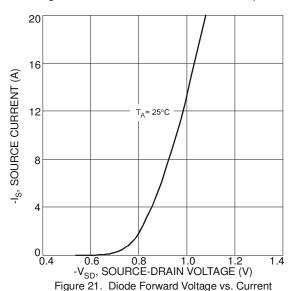
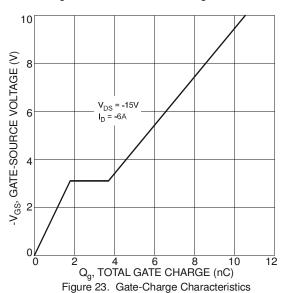


Figure 19. On-Resistance Variation with Temperature





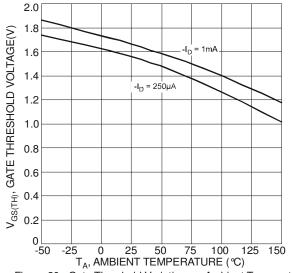
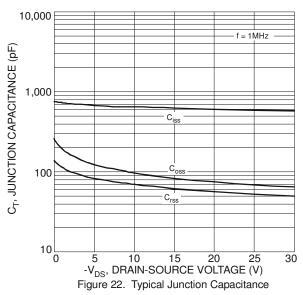


Figure 20. Gate Threshold Variation vs. Ambient Temperature



100

RDS(on)
Limited

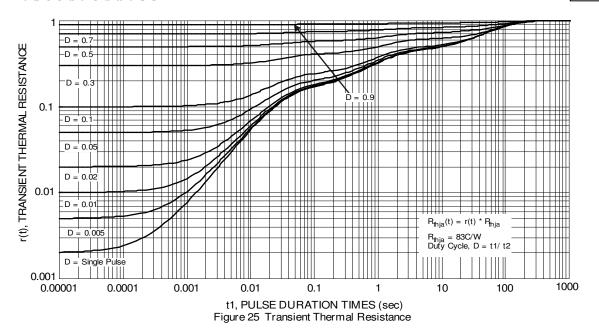
PW = 10µS

PW = 10µS

PW = 100mS

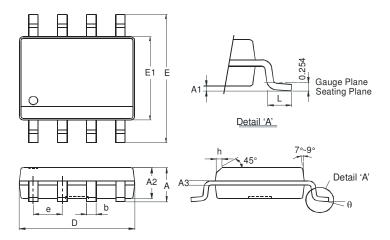
PW = 100m





#### **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

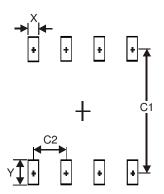


| SO-8                 |      |      |  |  |  |
|----------------------|------|------|--|--|--|
| Dim                  | Min  | Max  |  |  |  |
| Α                    | -    | 1.75 |  |  |  |
| A1                   | 0.10 | 0.20 |  |  |  |
| A2                   | 1.30 | 1.50 |  |  |  |
| А3                   | 0.15 | 0.25 |  |  |  |
| b                    | 0.3  | 0.5  |  |  |  |
| D                    | 4.85 | 4.95 |  |  |  |
| Е                    | 5.90 | 6.10 |  |  |  |
| E1                   | 3.85 | 3.95 |  |  |  |
| е                    | 1.27 | Тур  |  |  |  |
| h                    | -    | 0.35 |  |  |  |
| L                    | 0.62 | 0.82 |  |  |  |
| θ                    | 0°   | 8°   |  |  |  |
| All Dimensions in mm |      |      |  |  |  |

#### **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

#### **SO-8**



| Dimensions | Value (in mm) |
|------------|---------------|
| X          | 0.60          |
| Υ          | 1.55          |
| C1         | 5.4           |
| C2         | 1.27          |



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  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
- B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

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